MICROCHIP 24AA128/24LC128/24FC128

128K $I^2C^{™}$ CMOS Serial EEPROM

DEVICE SELECTION TABLE

Part Number	Vcc Range	Max Clock Frequency	Temp Ranges
24AA128	1.8-5.5V	400 kHz†	C
24LC128	2.5-5.5V	400 kHz‡	I, E
24FC128	2.5-5.5V	1 MHz	I

†100 kHz for VCC < 2.5V.
‡100 kHz for E temperature range.

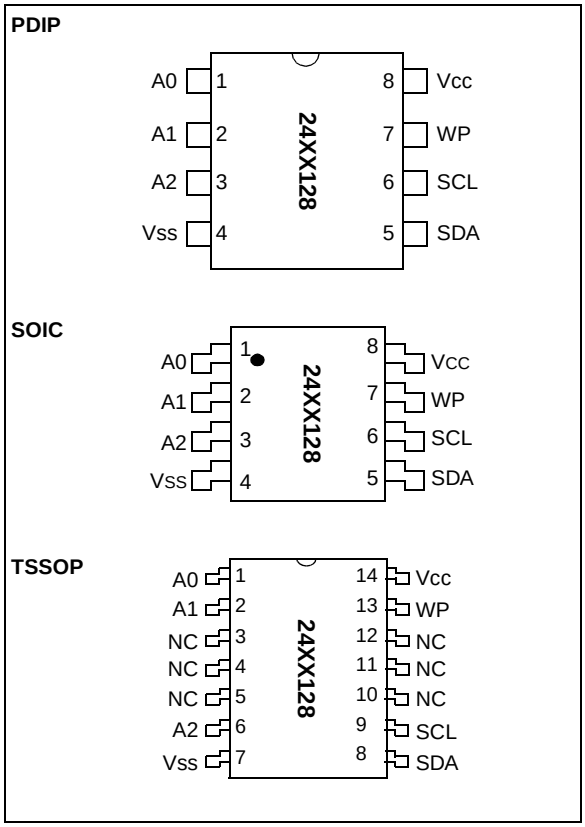
FEATURES

- Low power CMOS technology
  - Maximum write current 3 mA at 5.5V
  - Maximum read current 400 µA at 5.5V
  - Standby current 100 nA typical at 5.5V
- 2-wire serial interface bus, I^2C compatible
- Cascadable for up to eight devices
- Self-timed ERASE/WRITE cycle
- 64-byte page-write mode available
- 5 ms max write-cycle time
- Hardware write protect for entire array
- Output slope control to eliminate ground bounce
- Schmitt trigger inputs for noise suppression
- 100,000 erase/write cycles guaranteed
- Electrostatic discharge protection > 4000V
- Data retention > 200 years
- 8-pin PDIP and SOIC (150 and 208 mil) packages
- 14-pin TSSOP package
- Temperature ranges:
  - Commercial (C) 0° to +70°C
  - Industrial (I): -40°C to +85°C
  - Automotive (E): -40°C to +125°C

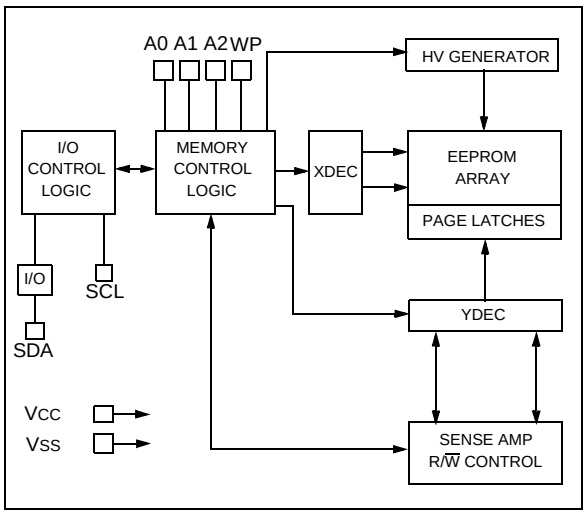
DESCRIPTION

The Microchip Technology Inc. 24AA128/24LC128/24FC128 (24XX128*) is a 16K x 8 (128K bit) Serial Electrically Erasable PROM, capable of operation across a broad voltage range (1.8V to 5.5V). It has been developed for advanced, low power applications such as personal communications or data acquisition. This device also has a page-write capability of up to 64 bytes of data. This device is capable of both random and sequential reads up to the 128K boundary. Functional address lines allow up to eight devices on the same bus, for up to 1M bit address space. This device is available in the standard 8-pin plastic DIP, 8-pin SOIC (150 and 208 mil), and 14-pin TSSOP packages.

PACKAGE TYPE



BLOCK DIAGRAM



I^2C is a trademark of Philips Corporation.
*24XX128 is used in this document as a generic part number for the 24AA128/24LC128/24FC128 devices.

1.0 ELECTRICAL CHARACTERISTICS

1.1 Maximum Ratings*

VCC.....6.5V
All inputs and outputs w.r.t. VSS .....-0.6V to VCC +1.0V
Storage temperature .....-65°C to +150°C
Ambient temp. with power applied.....-65°C to +125°C
Soldering temperature of leads (10 seconds) ..+300°C
ESD protection on all pins ..... ≥ 4 kV

***Notice:** Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: PIN FUNCTION TABLE

Name	Function
A0, A1, A2	User Configurable Chip Selects
VSS	Ground
SDA	Serial Data
SCL	Serial Clock
WP	Write Protect Input
VCC	+1.8 to 5.5V (24AA128) +2.5 to 5.5V (24LC128)

TABLE 1-2: DC CHARACTERISTICS

All parameters apply across the specified operating ranges, unless otherwise noted.	Commercial (C): VCC = +1.8V to 5.5V Tamb = 0°C to +70°C Industrial (I): VCC = +2.5V to 5.5V Tamb = -40°C to +85°C Automotive (E): VCC = +4.5V to 5.5V Tamb = -40°C to 125°C				
Parameter	**Symbol**	**Min**	**Max**	**Units**	**Conditions**
A0, A1, A2, SCL, SDA, and WP pins:					
High level input voltage	VIH	0.7 VCC	—	V	
Low level input voltage	VIL	—	0.3 VCC	V	VCC ≥ 2.5V
			0.2 VCC	V	VCC < 2.5V
Hysteresis of Schmitt Trigger inputs (SDA, SCL pins)	VHYS	0.05 VCC	—	V	VCC ≥ 2.5V (Note)
Low level output voltage	VOL	—	0.40	V	IOL = 3.0 mA @ VCC = 4.5V IOL = 2.1 mA @ VCC = 2.5V
Input leakage current	ILI	-10	10	µA	VIN = VSS or VCC, WP = VSS VIN = VSS or VCC, WP = VCC
Output leakage current	ILO	-10	10	µA	VOUT = VSS or VCC
Pin capacitance (all inputs/outputs)	CIN, COUT	—	10	pF	VCC = 5.0V (Note) Tamb = 25°C, f_c= 1 MHz
Operating current	ICC Read	—	400	µA	VCC = 5.5V, SCL = 400 kHz
	ICC Write	—	3	mA	VCC = 5.5V
Standby current	ICCS	—	1	µA	SCL = SDA = VCC = 5.5V A0, A1, A2, WP = VSS

Note: This parameter is periodically sampled and not 100% tested.

FIGURE 1-1: BUS TIMING DATA

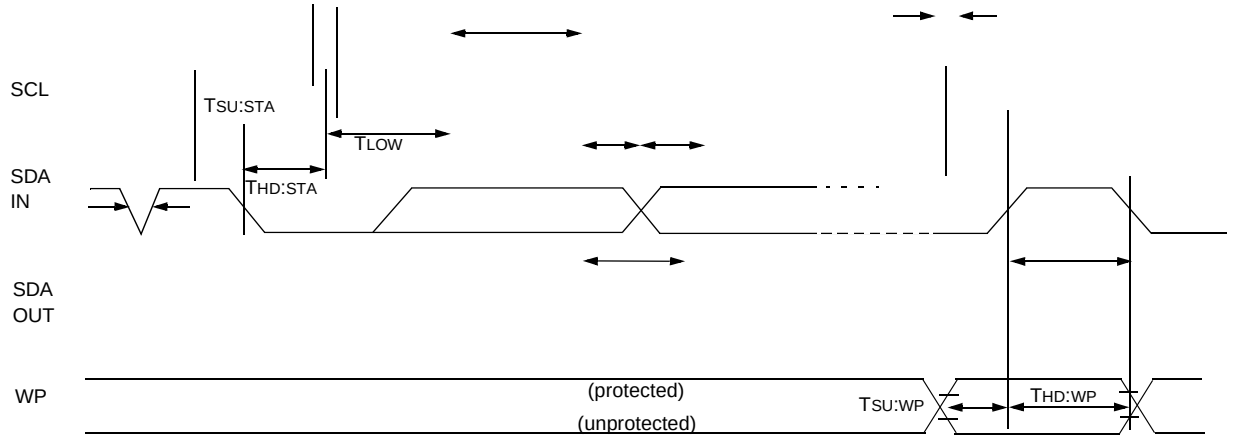


TABLE 1-3: AC CHARACTERISTICS

All parameters apply across the specified operating ranges unless otherwise noted.	Commercial (C): V_{CC} = +1.8V to 5.5V Tamb = 0°C to +70°C Industrial (I): V_{CC} = +2.5V to 5.5V Tamb = -40°C to +85°C Automotive (E): V_{CC} = +4.5V to 5.5V Tamb = -40°C to 125°C				
Parameter	Symbol	Min	Max	Units	Conditions
Clock frequency	F_{CLK}	—	100	kHz	4.5V ≤ Vcc ≤ 5.5V (E Temp range)
		—	100		1.8V ≤ Vcc ≤ 2.5V
		—	400		2.5V ≤ Vcc ≤ 5.5V
		—	1000		24FC128 (2.5 V ≤ Vcc ≤ 5.5 V)
Clock high time	T_{HIGH}	4000	—	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range)
		4000	—		1.8V ≤ Vcc ≤ 2.5V
		600	—		2.5V ≤ Vcc ≤ 5.5V
		500	—		24FC128 (2.5 V ≤ Vcc ≤ 5.5 V)
Clock low time	T_{LOW}	4700	—	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range)
		4700	—		1.8V ≤ Vcc ≤ 2.5V
		1300	—		2.5V ≤ Vcc ≤ 5.5V
		500	—		24FC128 (2.5 V ≤ Vcc ≤ 5.5 V)
SDA and SCL rise time (Note 1)	T_R	—	1000	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range)
		—	1000		1.8V ≤ Vcc ≤ 2.5V
		—	300		2.5V ≤ Vcc ≤ 5.5V
		—	300		24FC128 (2.5 V ≤ Vcc ≤ 5.5 V)
SDA and SCL fall time (Note 1)	T_F	—	300	ns	All except 24FC128
		—	100		24FC128 (2.5 V ≤ Vcc ≤ 5.5 V)
START condition hold time	$T_{HD:STA}$	4000	—	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range)
		4000	—		1.8V ≤ Vcc ≤ 2.5V
		600	—		2.5V ≤ Vcc ≤ 5.5V
		250	—		24FC128 (2.5 V ≤ Vcc ≤ 5.5 V)
START condition setup time	$T_{SU:STA}$	4700	—	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range)
		4700	—		1.8V ≤ Vcc ≤ 2.5V
		600	—		2.5V ≤ Vcc ≤ 5.5V
		250	—		24FC128 (2.5 V ≤ Vcc ≤ 5.5 V)
Data input hold time	$T_{HD:DAT}$	0	—	ns	(Note 2)
Data input setup time	$T_{SU:DAT}$	250	—	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range)
		250	—		1.8V ≤ Vcc ≤ 2.5V
		100	—		2.5V ≤ Vcc ≤ 5.5V
		100	—		24FC128 (2.5 V ≤ Vcc ≤ 5.5 V)
STOP condition setup time	$T_{SU:STO}$	4000	—	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range)
		4000	—		1.8V ≤ Vcc ≤ 2.5V
		600	—		2.5V ≤ Vcc ≤ 5.5V
		250	—		24FC128 (2.5 V ≤ Vcc ≤ 5.5 V)
WP setup time	$T_{SU:WP}$	4000	—	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range)
		4000	—		1.8V ≤ Vcc ≤ 2.5V
		600	—		2.5V ≤ Vcc ≤ 5.5V
		600	—		24FC128 (2.5 V ≤ Vcc ≤ 5.5 V)
WP hold time	$T_{HD:WP}$	4700	—	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range)
		4700	—		1.8V ≤ Vcc ≤ 2.5V
		1300	—		2.5V ≤ Vcc ≤ 5.5V
		1300	—		24FC128 (2.5 V ≤ Vcc ≤ 5.5 V)

Note 1: Not 100% tested. C_B = total capacitance of one bus line in pF.

2: As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

3: The combined T_{SP} and V_{HYS} specifications are due to new Schmitt trigger inputs which provide improved noise spike suppression. This eliminates the need for a TI specification for standard operation.

4: This parameter is not tested but guaranteed by characterization. For endurance estimates in a specific application, please consult the Total Endurance Model which can be obtained on Microchip's BBS or website.

TABLE 1-3: AC CHARACTERISTICS (CONTINUED)

All parameters apply across the specified operating ranges unless otherwise noted.	Commercial (C): VCC = +1.8V to 5.5V Tamb = 0°C to +70°C Industrial (I): VCC = +2.5V to 5.5V Tamb = -40°C to +85°C Automotive (E): VCC = +4.5V to 5.5V Tamb = -40°C to 125°C				
Parameter	Symbol	Min	Max	Units	Conditions
Output valid from clock (Note 2)	TAA	— — — —	3500 3500 900 400	ns	4.5V ≤ VCC ≤ 5.5V (E Temp range) 1.8V ≤ VCC ≤ 2.5V 2.5V ≤ VCC ≤ 5.5V 24FC128 (2.5 V ≤ Vcc ≤ 5.5 V)
Bus free time: Time the bus must be free before a new transmission can start	TBUF	4700 4700 1300 500	— — — —	ns	4.5V ≤ VCC ≤ 5.5V (E Temp range) 1.8V ≤ VCC ≤ 2.5V 2.5V ≤ VCC ≤ 5.5V 24FC128 (2.5 V ≤ Vcc ≤ 5.5 V)
Output fall time from VIH minimum to VIL maximum $C_B \leq 100$ pF	TOF	$10 + 0.1C_B$	250 250	ns	All except 24FC128 (Note 1) 24FC128 (Note 1)
Input filter spike suppression (SDA and SCL pins)	TSP	—	50	ns	All except 24FC128 (Notes 1 and 3)
Write cycle time (byte or page)	TWC	—	5	ms	
Endurance		100K	—	cycles	25°C, VCC = 5.0V, Block Mode (Note 4)

Note 1: Not 100% tested. C_B = total capacitance of one bus line in pF.

2: As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

3: The combined TSP and VHYS specifications are due to new Schmitt trigger inputs which provide improved noise spike suppression. This eliminates the need for a TI specification for standard operation.

4: This parameter is not tested but guaranteed by characterization. For endurance estimates in a specific application, please consult the Total Endurance Model which can be obtained on Microchip's BBS or website.

2.0 PIN DESCRIPTIONS

2.1 A0, A1, A2 Chip Address Inputs

The A0, A1, A2 inputs are used by the 24XX128 for multiple device operations. The levels on these inputs are compared with the corresponding bits in the slave address. The chip is selected if the compare is true.

Up to eight devices may be connected to the same bus by using different chip select bit combinations. If left unconnected, these inputs will be pulled down internally to VSS.

2.2 SDA Serial Data

This is a bi-directional pin used to transfer addresses and data into and data out of the device. It is an open-drain terminal, therefore, the SDA bus requires a pullup resistor to VCC (typical 10 kΩ for 100 kHz, 2 kΩ for 400 kHz and 1 MHz).

For normal data transfer SDA is allowed to change only during SCL low. Changes during SCL high are reserved for indicating the START and STOP conditions.

2.3 SCL Serial Clock

This input is used to synchronize the data transfer from and to the device.

2.4 WP

This pin can be connected to either VSS, VCC or left floating. An internal pull-down resistor on this pin will keep the device in the unprotected state if left floating. If tied to VSS or left floating, normal memory operation is enabled (read/write the entire memory 0000-3FFF).

If tied to VCC, WRITE operations are inhibited. Read operations are not affected.

3.0 FUNCTIONAL DESCRIPTION

The 24XX128 supports a bi-directional 2-wire bus and data transmission protocol. A device that sends data onto the bus is defined as a transmitter, and a device receiving data as a receiver. The bus must be controlled by a master device which generates the serial clock (SCL), controls the bus access, and generates the START and STOP conditions while the 24XX128 works as a slave. Both master and slave can operate as a transmitter or receiver, but the master device determines which mode is activated.

4.0 BUS CHARACTERISTICS

The following **bus protocol** has been defined:

- Data transfer may be initiated only when the bus is not busy.
- During data transfer, the data line must remain stable whenever the clock line is HIGH. Changes in the data line while the clock line is HIGH will be interpreted as a START or STOP condition.

Accordingly, the following bus conditions have been defined (Figure 4-1).

4.1 Bus not Busy (A)

Both data and clock lines remain HIGH.

4.2 Start Data Transfer (B)

A HIGH to LOW transition of the SDA line while the clock (SCL) is HIGH determines a START condition. All commands must be preceded by a START condition.

4.3 Stop Data Transfer (C)

A LOW to HIGH transition of the SDA line while the clock (SCL) is HIGH determines a STOP condition. All operations must end with a STOP cona810(Glaq1.008 T]TJı˝T*ı˝0.003 Tcı˝-0.001 Twı˝[(o)12(per)16(at)14(9))]T(Glaq1.-a-22(t) V)52t S
4 ln12(202)-perat143-11 ml20

5.0 DEVICE ADDRESSING

A control byte is the first byte received following the start condition from the master device (Figure 5-1). The control byte consists of a 4-bit control code; for the 24XX128 this is set as 1010 binary for read and write operations. The next three bits of the control byte are the chip select bits (A2, A1, A0). The chip select bits allow the use of up to eight 24XX128 devices on the same bus and are used to select which device is accessed. The chip select bits in the control byte must correspond to the logic levels on the corresponding A2, A1, and A0 pins for the device to respond. These bits are in effect the three most significant bits of the word address.

The last bit of the control byte defines the operation to be performed. When set -13lor oTJ 07(7e-1(s0)-1(9T86 [()12(te)27(s)10(e)-1(l)12(e)-1()1( )]T812(e)--247(7e-2(s)-4(s)l)12(, 0.0n12(r(l

6.0 WRITE OPERATIONS

6.1 Byte Write

Following the start condition from the master, the control code (four bits), the chip select (three bits), and the R/W bit (which is a logic low) are clocked onto the bus by the master transmitter. This indicates to the addressed slave receiver that the address high byte will follow after it has generated an acknowledge bit during the ninth clock cycle. Therefore, the next byte transmitted by the master is the high-order byte of the word address and will be written into the address pointer of the 24XX128. The next byte is the least significant address byte. After receiving another acknowledge signal from the 24XX128, the master device will transmit the data word to be written into the addressed memory location. The 24XX128 acknowledges again and the master generates a stop condition. This initiates the internal write cycle, and, during this time, the 24XX128 will not generate acknowledge signals (Figure 6-1). If an attempt is made to write to the array with the WP pin held high, the device will acknowledge the command but no write cycle will occur, no data will be written, and the device will immediately accept a new command. After a byte write command, the internal address counter will point to the address location following the one that was just written.

6.2 Page Write

The write control byte, word address, and the first data byte are transmitted to the 24XX128 in the same way as in a byte write. But instead of generating a stop condition, the master transmits up to 63 additional bytes, which are temporarily stored in the on-chip page buffer and will be written into memory after the master has transmitted a stop condition. After receipt of each word, the six lower address pointer bits are internally incremented by one. If the master should transmit more than 64 bytes prior to generating the stop condition, the address counter will roll over and the previously received data will be overwritten. As with the byte write operation, once the stop condition is received, an internal write cycle will begin (Figure 6-2). If an attempt is made to write to the array with the WP pin held high, the device will acknowledge the command but no write cycle will occur, no data will be written, and the device will immediately accept a new command.

6.3 Write Protection

The WP pin allows the user to write-protect the entire array (0000-3FFF) when the pin is tied to VCC. If tied to VSS or left floating, the write protection is disabled. The WP pin is sampled at the STOP bit for every write command (Figure 1-1) Toggling the WP pin after the STOP bit will have no effect on the execution of the write cycle.

Note:	Page write operations are limited to writing bytes within a single physical page, regardless of the number of bytes actually being written. Physical page boundaries start at addresses that are integer multiples of the page buffer size (or 'page size') and end at addresses that are integer multiples of [page size - 1]. If a page write command attempts to write across a physical page boundary, the result is that the data wraps around to the beginning of the current page (overwriting data previously stored there), instead of being written to the next page as might be expected. It is therefore necessary for the application software to prevent page write operations that would attempt to cross a page boundary.

FIGURE 6-1: BYTE WRITE

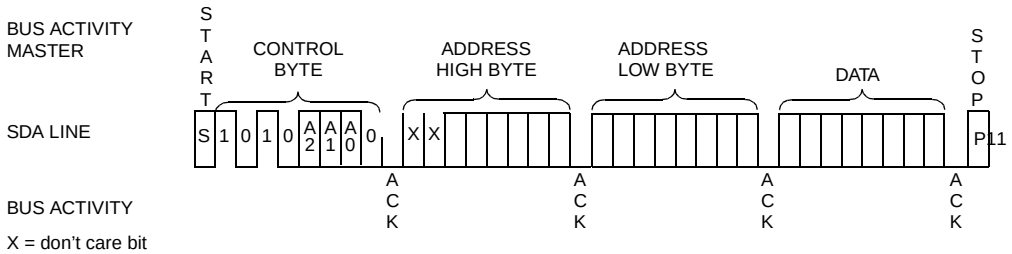
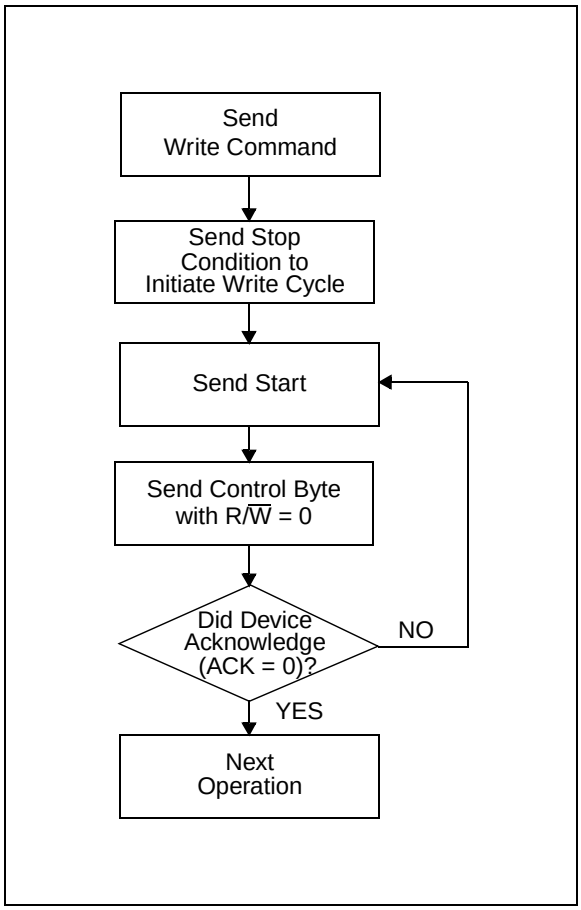


FIGURE 6-2: PAGE WRITE

7.0 ACKNOWLEDGE POLLING

Since the device will not acknowledge during a write cycle, this can be used to determine when the cycle is complete (This feature can be used to maximize bus throughput.) Once the stop condition for a write command has been issued from the master, the device initiates the internally timed write cycle. ACK polling can be initiated immediately. This involves the master sending a start condition, followed by the control byte for a write command (R/$\overline{W}$ = 0). If the device is still busy with the write cycle, then no ACK will be returned. If no ACK is returned, then the start bit and control byte must be resent. If the cycle is complete, then the device will return the ACK, and the master can then proceed with the next read or write command. See Figure 7-1 for flow diagram.

FIGURE 7-1: ACKNOWLEDGE POLLING FLOW



8.0 READ OPERATION

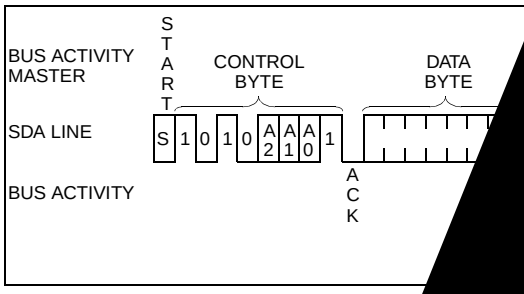
Read operations are initiated in the same way as write operations with the exception that the R/$\overline{W}$ bit of the control byte is set to one. There are three basic types of read operations: current address read, random read, and sequential read.

8.1 Current Address Read

The 24XX128 contains an address counter that maintains the address of the last word accessed, internally incremented by one. Therefore, if the previous read access was to address n (n is any legal address), the next current address read operation would access data from address n + 1.

Upon receipt of the control byte with R/$\overline{W}$ bit set to one, the 24XX128 issues an acknowledge and transmits the 8-bit data word. The master will not acknowledge the transfer but does generate a stop condition and the 24XX128 discontinues transmission (Figure 8-1).

FIGURE 8-1: CURRENT ADDRESS READ



8.2 Ra ead

Random ons allow the master to access any mem n a random manner. To perform this type tion, first the word address must be set sending the word address to the 24XX rite operation (R/$\overline{W}$ bit set to 0). After is sent, the master generates a sta g the acknowledge. This termina on, but not before the internal a Then, the master issues the ith the R/$\overline{W}$ bit set to a one. The e an acknowledge and transmit e master will not acknowledge enerate a stop condition which to discontinue transmission dom read command, the inter- point to the address location as just read.

ead

ated in the same way as a ran- er the 24XX128 transmits the er issues an acknowledge as dition used in a random read. the 24XX128 to transmit the sed 8-bit word (Figure 8-3). ransmitted to the master, the an acknowledge but will gen- provide sequential reads, the rnal address pointer which is e completion of each opera- r allows the entire memory d during one operation. The ll automatically roll over from 0000 if the master acknowl- om the array address 3FFF.

FIGURE 8-2: RANDOM RE

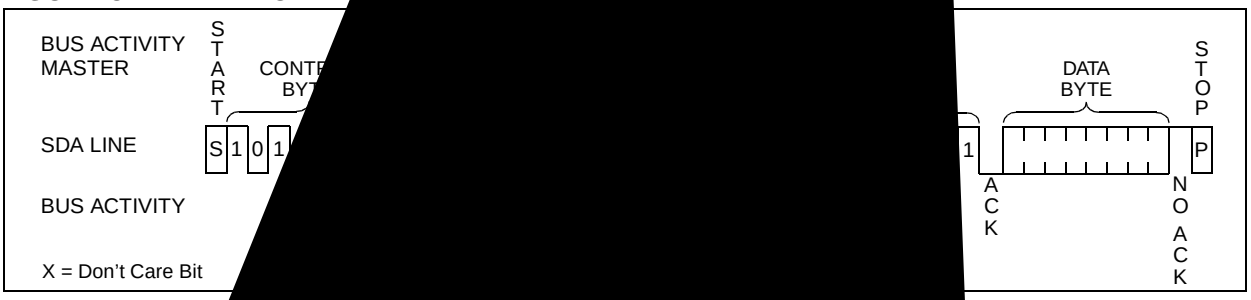
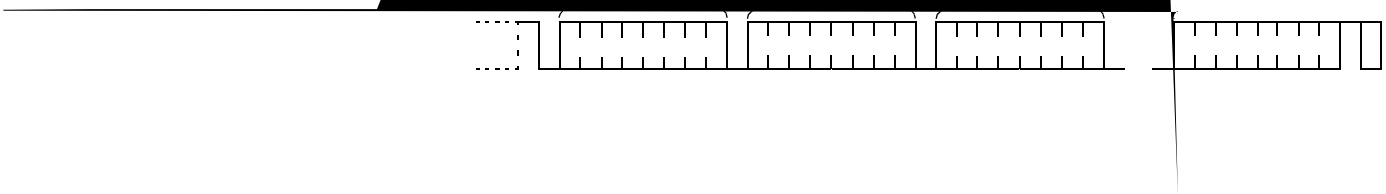


FIGURE 8-3: S



NOTES:

24XX128 PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

24XX128 — /P

Package:

P	=	Plastic DIP (300 mil Body), 8-lead
SN	=	Plastic SOIC (150 mil Body)
ST	=	TSSOP, 8-lead
OT	=	SOT-23, 5-lead

Temperature Range:

Blank	=	0°C to +70°C
I	=	–40°C to +85°C
E	=	–40°C to +125°C

Device:

24AA128	128 bit 1.8V I^2C Serial EEPROM
24AA128T	128 bit 1.8V K I^2C Serial EEPROM (Tape and Reel)
24LC128	128 bit 2.5V I^2C Serial EEPROM
24LC128T	128 bit 2.5V K I^2C Serial EEPROM (Tape and Reel)
24FC128	128 bit 1MHz I^2C Serial EEPROM
24FC128T	128 bit 1MHz I^2C Serial EEPROM (Tape and Reel)

Sales and Support

Data Sheets
Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (602) 786-7277. After September 1, 1999, (480) 786-7277
3. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

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Two Prestige Place, Suite 150
Miamisburg, OH 45342
Tel: 937-291-1654 Fax: 937-291-9175

Detroit
Microchip Technology Inc.
Tri-Atria Office Building
32255 Northwestern Highway, Suite 190
Farmington Hills, MI 48334
Tel: 248-538-2250 Fax: 248-538-2260

Los Angeles
Microchip Technology Inc.
18201 Von Karman, Suite 1090
Irvine, CA 92612
Tel: 949-263-1888 Fax: 949-263-1338

New York
Microchip Technology Inc.
150 Motor Parkway, Suite 202
Hauppauge, NY 11788
Tel: 631-273-5305 Fax: 631-273-5335

San Jose
Microchip Technology Inc.
2107 North First Street, Suite 590
San Jose, CA 95131
Tel: 408-436-7950 Fax: 408-436-7955

AMERICAS (continued)

Toronto
Microchip Technology Inc.
5925 Airport Road, Suite 200
Mississauga, Ontario L4V 1W1, Canada
Tel: 905-405-6279 Fax: 905-405-6253

ASIA/PACIFIC

Hong Kong
Microchip Asia Pacific
Unit 2101, Tower 2
Metroplaza
223 Hing Fong Road
Kwai Fong, N.T., Hong Kong
Tel: 852-2-401-1200 Fax: 852-2-401-3431

Beijing
Microchip Technology, Beijing
Unit 915, 6 Chaoyangmen Bei Dajie
Dong Erhuan Road, Dongcheng District
New China Hong Kong Manhattan Building
Beijing 100027 PRC
Tel: 86-10-85282100 Fax: 86-10-85282104

India
Microchip Technology Inc.
India Liaison Office
No. 6, Legacy, Convent Road
Bangalore 560 025, India
Tel: 91-80-229-0061 Fax: 91-80-229-0062

Japan
Microchip Technology Intl. Inc.
Benex S-1 6F
3-18-20, Shinyokohama
Kohoku-Ku, Yokohama-shi
Kanagawa 222-0033 Japan
Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea
Microchip Technology Korea
168-1, Youngbo Bldg. 3 Floor
Samsung-Dong, Kangnam-Ku
Seoul, Korea
Tel: 82-2-554-7200 Fax: 82-2-558-5934

Shanghai
Microchip Technology
RM 406 Shanghai Golden Bridge Bldg.
2077 Yan'an Road West, Hong Qiao District
Shanghai, PRC 200335
Tel: 86-21-6275-5700 Fax: 86 21-6275-5060

ASIA/PACIFIC (continued)

Singapore
Microchip Technology Singapore Pte Ltd.
200 Middle Road
#07-02 Prime Centre
Singapore 188980
Tel: 65-334-8870 Fax: 65-334-8850

Taiwan, R.O.C
Microchip Technology Taiwan
10F-1C 207
Tung Hua North Road
Taipei, Taiwan, ROC
Tel: 886-2-2717-7175 Fax: 886-2-2545-0139

EUROPE

United Kingdom
Arizona Microchip Technology Ltd.
505 Eskdale Road
Winnersh Triangle
Wokingham
Berkshire, England RG41 5TU
Tel: 44 118 921 5858 Fax: 44-118 921-5835

Denmark
Microchip Technology Denmark ApS
Regus Business Centre
Lautrup hoj 1-3
Ballerup DK-2750 Denmark
Tel: 45 4420 9895 Fax: 45 4420 9910

France
Arizona Microchip Technology SARL
Parc d'Activite du Moulin de Massy
43 Rue du Saule Trapu
Batiment A - ler Etage
91300 Massy, France
Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany
Arizona Microchip Technology GmbH
Gustav-Heinemann-Ring 125
D-81739 München, Germany
Tel: 49-89-627-144 0 Fax: 49-89-627-144-44

Italy
Arizona Microchip Technology SRL
Centro Direzionale Colleoni
Palazzo Taurus 1 V. Le Colleoni 1
20041 Agrate Brianza
Milan, Italy
Tel: 39-039-65791-1 Fax: 39-039-6899883

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